

MOSFET - Power, N-Channel, SUPERFET[®] III, FRFET[®]

650 V, 40 mΩ, 65 A NVHL040N65S3HF

Description

SUPERFET III MOSFET is **onsemi**'s brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III HF version provides fast recovery for improved efficiency in high speed switching applications.

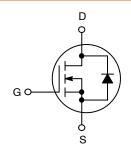
Features

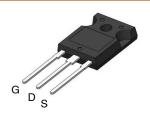
- $700 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 31 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q_g = 157 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 1374 pF)
- 100% Avalanche Tested
- NVHL Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Automotive On Board Charger HEV-EV
- Automotive DC/DC Converter for HEV-EV

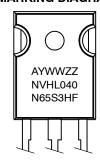
V _{DSS}	R _{DS(ON)} MAX	I _D MAX
650 V	40 mΩ @ 10 V	65 A





TO-247 Long Leads CASE 340CX

MARKING DIAGRAM



A = Assembly Plant Code
YWW = Data Code (Year & Week)
ZZ = Assembly Lot Code
NVHL040N65S3HF = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Downloaded from Arrow.com.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$, Unless otherwise noted)

Symbol	Parameter	Value	Unit			
V_{DSS}	Drain-to-Source Voltage	o-Source Voltage		V		
V_{GSS}	Gate-to-Source Voltage	- DC		- DC ±3	±30	V
		- AC (f > 1 Hz)	±30			
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		А		
				1		
I _{DM}	Drain Current	- Pulsed (Note 1)	162.5	А		
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	1009	mJ			
I _{AS}	Avalanche Current (Note 2)	9	А			
E _{AR}	Repetitive Avalanche Energy (Note 1)	4.46	mJ			
dv/dt	MOSFET dv/dt	, , , , , , , , , , , , , , , , , , ,		V/ns		
	Peak Diode Recovery dv/dt (Note 3)					
P_{D}	Power Dissipation (T _C = 25°C)		446	W		
		- Derate Above 25°C	3.57	W/°C		
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C		
TL	Maximum Lead Temperature for Soldering, 1/8"	300	°C			

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive rating: pulse–width limited by maximum junction temperature.
2. $I_{AS} = 9 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$.
3. $I_{SD} \le 32.5 \text{ A}$, $di/dt \le 200 \text{ A}/\mu\text{s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.28	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	

PACKAGE MARKING AND ORDERING INFORMATION

ĺ	Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
ĺ	NVHL040N65S3HF	NVHL040N65S3HF	TO-247	Tube	N/A	N/A	30 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARAC	TERISTICS			•	•	
BV _{DSS}	Drain-to-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 1 \text{ mA, } T_J = 25^{\circ}\text{C}$	650	-	_	V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700	-	-	V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 15 mA, Referenced to 25°C	-	0.63	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	_	10	μΑ
		V _{DS} = 520 V, T _C = 125°C	-	28	_	
I _{GSS}	Gate-to-Body Leakage Current	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	_	±100	nA
ON CHARACT	ERISTICS				-	
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 2.1 \text{ mA}$	3.0	_	5.0	V
R _{DS(on)}	Static Drain-to-Source On Resistance	V _{GS} = 10 V, I _D = 32.5 A	-	31	40	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 32.5 A	-	45	_	S
DYNAMIC CHA	ARACTERISTICS				-	
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz	-	6655	_	pF
C _{oss}	Output Capacitance	1		143	_	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	1374	_	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	250	-	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 32.5 A, V _{GS} = 10 V	-	157	_	nC
Q _{gs}	Gate-to-Source Gate Charge	(Note 4)		49	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge		-	61	_	nC
ESR	Equivalent Series Resistance	f = 1 MHz	_	1.1	_	Ω
SWITCHING C	HARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, I_D = 32.5 \text{ A},$	-	42.2	_	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_g = 2.2 Ω (Note 4)	-	27.4	_	ns
t _{d(off)}	Turn-Off Delay Time		-	103	_	ns
t _f	Turn-Off Fall Time		-	3.4	_	ns
SOURCE-DRA	IN DIODE CHARACTERISTICS					
Is	Maximum Continuous Source-to-Drain Diode Forward Current		-	_	65	Α
I _{SM}	Maximum Pulsed Source-to-Drain Dio	rce-to-Drain Diode Forward Current		_	162.5	Α
V_{SD}	Source-to-Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 32.5 A	-	_	1.3	٧
t _{rr}	Reverse Recovery Time	$V_{DD} = 400 \text{ V}, I_{SD} = 32.5 \text{ A},$	_	137	_	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs		792	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL CHARACTERISTICS

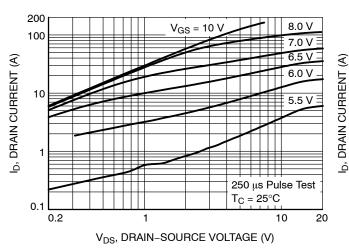


Figure 1. On-Region Characteristics

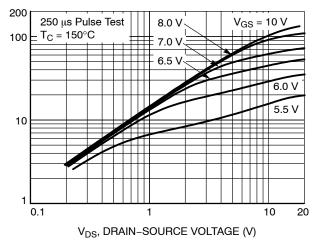


Figure 2. On-Region Characteristics

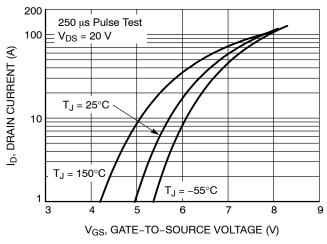


Figure 3. Transfer Characteristics

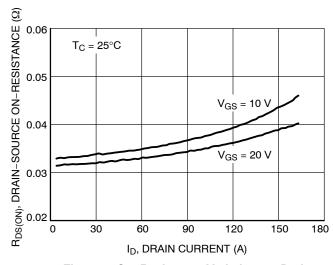


Figure 4. On-Resistance Variation vs. Drain Current and Gate Voltage

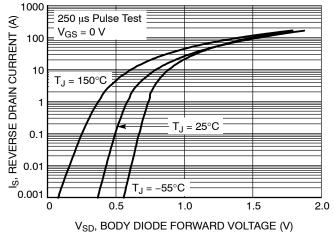


Figure 5. Body Diode Forward Voltage Variation vs. Source Current and Temperature

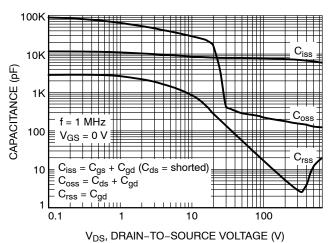
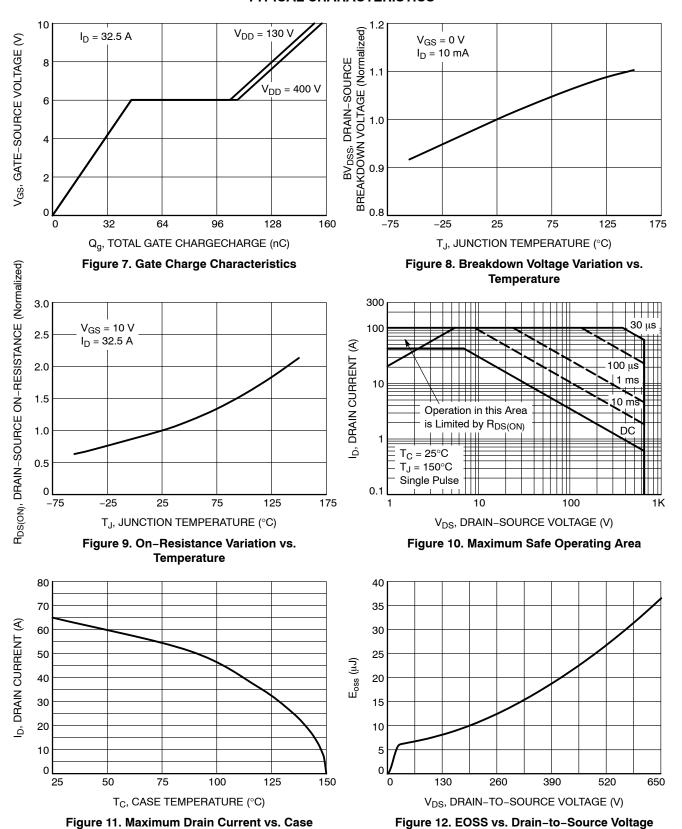


Figure 6. Capacitance Characteristics

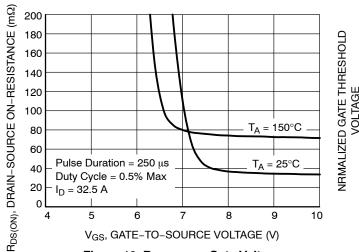
TYPICAL CHARACTERISTICS



Temperature

TYPICAL CHARACTERISTICS

1.2



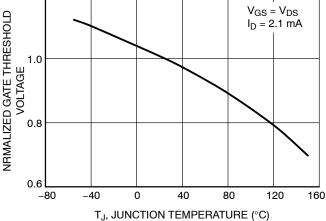
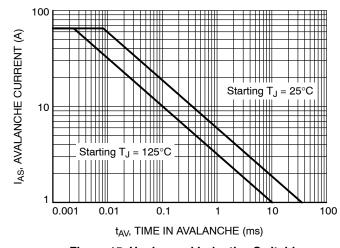


Figure 13. R_{DS(ON)} vs. Gate Voltage

Figure 14. Normalized Gate Threshold Voltage vs. Temperature



$$\begin{split} &\text{If R} = 0 \\ &t_{AV} = (L)(I_{AS})/(1.3*\text{RATED BV}_{DSS} - V_{DD}) \\ &\text{If R} \neq 0 \\ &t_{AV} = (L/R)In[(I_{AS}*R)/(1.3*\text{RATED BV}_{DSS} - V_{DD}) + 1] \end{split}$$

NOTE: Refer to Application Notes AN7514 and AN7515

Figure 15. Unclamped Inductive Switching Capability

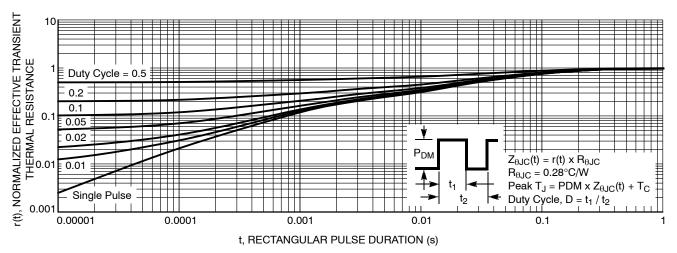


Figure 16. Transient Thermal Response Curve

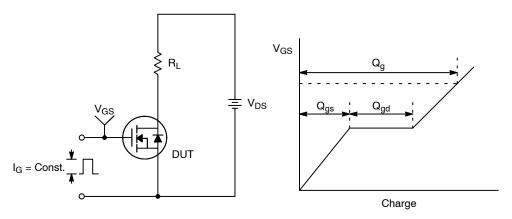


Figure 17. Gate Charge Test Circuit & Waveform

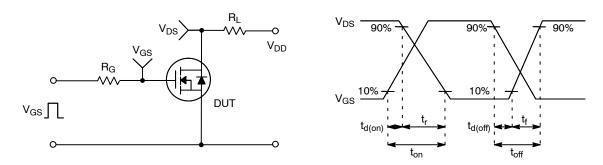


Figure 18. Resistive Switching Test Circuit & Waveforms

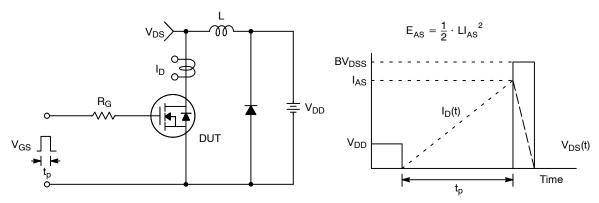


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms

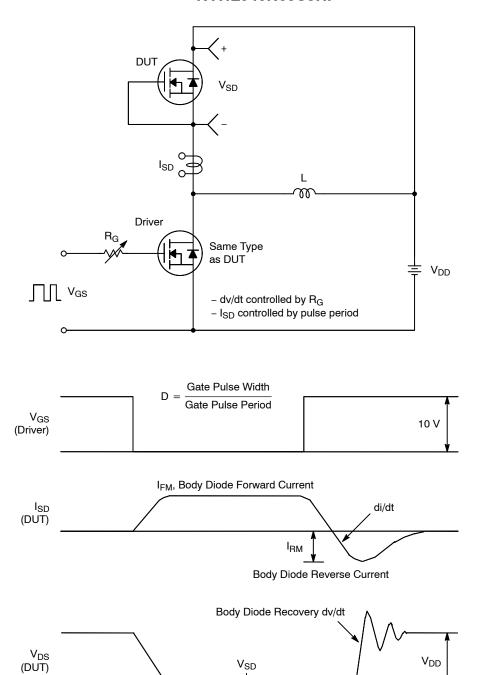


Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

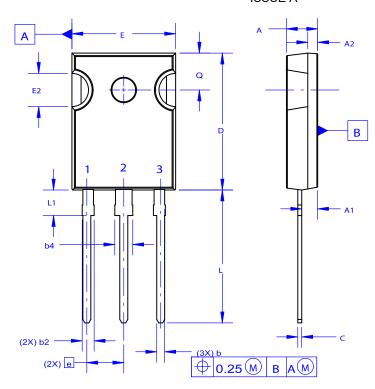
 V_{SD}

Body Diode Forward Voltage Drop $V_{DD} \\$

SUPERFET and FRFET are a registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries.

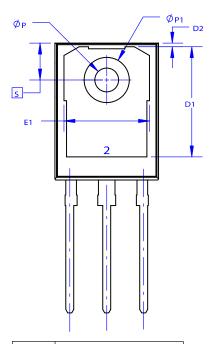
PACKAGE DIMENSIONS

TO-247-3LD CASE 340CX **ISSUE A**



NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN NOM M		MAX		
Α	4.58	4.58 4.70 4.82			
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.37 15.62 15.8			
E2	4.96	5.08	5.20		
е	~ 5.56		~		
L	L 19.75 2		20.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46 5.5			
b	1.17	1.26	1.35		
b2	1.53 1.65 1.		1.77		
b4	2.42 2.54 2		2.66		
С	0.51 0.61		0.71		
D1	13.08	.08 ~ ~			
D2	0.51	0.93			
E1	12.81	81 ~ ~			
ØP1	6.60	6.80	7.00		

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

onsemi Website: www.onsemi.com

0